

**1206L020/30NRT**

Surface Mount PPTC Devices

**Features**

- Size 0.12\*0.06 inch /3.2\*1.6 mm
- Surface mount resettable fuse
- Temperature Range:-40°C-125°C
- Fast time-to-trip
- Low resistance
- Compatible with high temperature solders

**Electrical Characteristics (25°C)/电性参数**

Part Number	Marking	I <sub>hold</sub> (A)	I <sub>trip</sub> (A)	V <sub>max</sub> (Vdc)	I <sub>max</sub> (A)	P <sub>d</sub> typ. (W)	Time to Trip (Max.)		Resistance	
							Current (A)	Time (Sec)	R min (Ω)	R 1max (Ω)
1206L020/30NRT	0.20	0.50	30	10	0.9	8.00	0.10	0.60	4.50	4.50

I<sub>hold</sub> = Hold current: maximum current device will pass without tripping in 25°C still air. 保持电流=在 25°C 静止空气环境中,元件不动作的最大电流。

I<sub>trip</sub> = Trip current: minimum current at which the device will trip in 25°C still air. 动作电流=在 25°C 静止空气环境中,元件的最小动作电流。

V<sub>max</sub> = Maximum voltage device can withstand without damage at rated current (I<sub>max</sub>). 最大电压=元件在额定电流下能承受的最大电压。

I<sub>max</sub> = Maximum fault current device can withstand without damage at rated voltage (V<sub>max</sub>). 最大电流=元件在额定电压下能承受的最大电流。

P<sub>d</sub> typ. = Typical power dissipated from device when in the tripped state at 25°C still air. 动作功率=在 25°C 静止空气环境中,元件动作状态下的消耗功率。

T<sub>trip</sub> = Maximum time to trip(s) at assigned current reflow soldering of 260°C for 20 sec. 动作时间=5 倍保持电流下的最大动作时间。

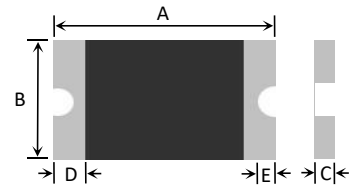
R<sub>min</sub> = Minimum resistance of device in initial (un-soldered) state. 初始最小电阻=元件焊接前的初始最小阻值。

R<sub>1max</sub> = Maximum resistance of device at 25°C measured one hour after tripping or reflow soldering of 260°C for 20 sec. 焊后最大电阻=元件焊接 1 小时后的最大阻值。

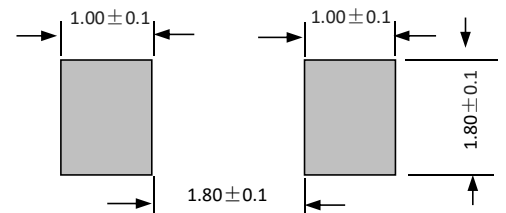
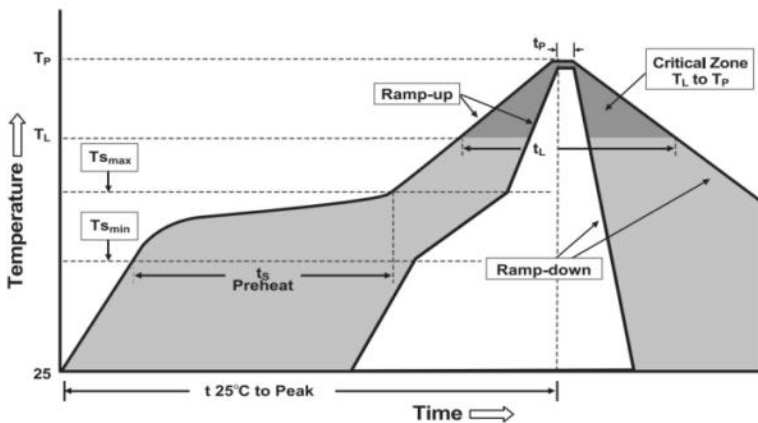
**Caution** : Operation beyond the specified rating may result in damage and possible arcing and flame. 注意: 超出指定额定值的操作, 可能会导致损伤并可能产生电弧和火焰。

**Product Dimensions(mm)/产品尺寸**

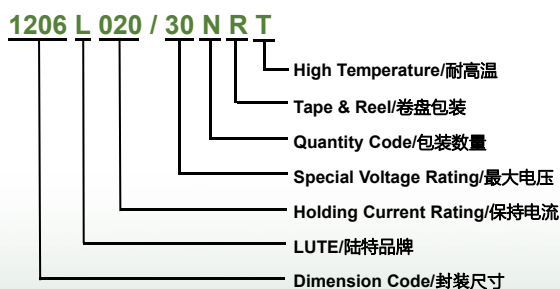
Part Number	QTY	A		B		C		D	E
		Min	Max	Min	Max	Min	Max	Min	Min
1206L020/30NRT	3500	3.00	3.60	1.50	1.90	0.40	1.00	0.40	0.20


**Temperature Derating/PPTC 在不同温度下的热降额**

TEMPERATURE	Thermal Derating for PPTC Device at Various Ambient Temperatures								
	-40°C	-20°C	0°C	23°C	40°C	60°C	85°C	100°C	125°C
DERATING %	135%	122%	110%	100%	90%	75%	65%	53%	40%

**Solder Reflow Recommendations/回流焊建议**


Recommended Pad Layout (mm)  
建议焊盘布局 (mm)

**Part Number System/产品编号**

**Agency Approvals/认证**

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Specifications are subject to change without notice

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